ABLEBOND® AAA3310

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PRODUCT DESCRIPTION

ABLEBOND® AAA3310 provides the following product characteristics:

Technology	Epoxy
Appearance	Amber
Cure	Heat cure
Product Benefits	• Very low modulus • Self Filleting™ • Low bleed • Long work life • Non-conductive • Excellent MSL 260ºC performance • Low warpage for large thin die on thin substrate • Good adhesion to a variety of organic substrates
Application	Die attach

ABLEBOND® AAA3310 adhesive is designed to resolve substrate warpage problems arising from attaching large die on thin organic substrates. The Self-Filleting™ feature is ideal for tight tolerance applications.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Viscosity, Brookfield CP51, 25 °C, mPa·s (cP):	
Speed 5 rpm	10,000
Work Life @ 25°C, hours	48
Shelf Life @ -40°C (from date of manufacture), year	1

TYPICAL CURING PERFORMANCE

Cure Schedule

30 minute ramp to 175°C + 15 minutes @ 175°C

Alternative Cure Schedule

30 minutes ramp to 150°C + 30 minutes @ 175°C

** Self-Filleting™ can be achieved with box oven or snap cure oven with controllable ramp up rate (3 to 5ºC/ minute).*
** Self-Filleting™ is not recommended on die bonder spot cure with instantaneous ramp.*
** To achieve better Self-Filleting™ effect, the material can be held isothermal at 45ºC for a minimum of 20 minutes in the ramp-up phase. This process will depend on the application and adjustments may be made depending on the package type.*

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties:

Coefficient of Thermal Expansion :		
Below Tg, ppm/°C		80
Above Tg, ppm/°C		174
Glass Transition Temperature (Tg) by TMA, °C		-27
Thermal Conductivity @ 121°C, W/mK		0.27
Tensile Modulus, DMTA :		
@ -65 °C	N/mm² (psi)	2,200 (319,083)
@ 25 °C	N/mm² (psi)	42 (6,091)
@ 150 °C	N/mm² (psi)	16 (2,320)
@ 200 °C	N/mm² (psi)	20 (2,900)
@ 250 °C	N/mm² (psi)	25 (3,625)
Extractable Ionic Content, ppm:		
Chloride (Cl-)		≤20
Sodium (Na+)		≤20
Potassium (K+)		≤20
Weight Loss @ 175ºC, %		<1
Moisture Absorption @ Saturation, wt.% @ 85°C/85°RH		≤0.6

Electrical Properties:

Volume Resistivity, ohms-cm	$>1\times10^{13}$

TYPICAL PERFORMANCE OF CURED MATERIAL

Die Shear Strength:

2 X 2 mm Si die, kg-f,

Substrate	@25°C
Ceramic	7

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

THAWING:

1. Allow container to reach room temperature before use.
2. After removing from the freezer, set the syringes to stand vertically while thawing.
3. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
4. DO NOT re-freeze. Once thawed to -40°C, the adhesive should not be re-frozen.

DIRECTIONS FOR USE

1. Thawed adhesive should be immediately placed on dispense equipment for use.
2. If the adhesive is transferred to a final dispensing reservoir, care must be exercised to avoid entrapment of contaminants and/or air into the adhesive.
3. Adhesive must be completely used within the product's recommended work life.
4. Apply enough adhesive to achieve a 25 to 50 µm wet bondline thickness, dispensed with approximately 25 to 50 % filleting on all sides of the die.
5. Alternate dispense amounts may be used depending on the application requirements.
6. Star or crossed shaped dispense patterns will yield fewer bondline voids that the matrix style of dispense pattern.
7. To make use of the Self-Filleting™ feature, dispense a pattern as normal, but attach the die to a height taller than the desired bondline WITHOUT forming a fillet.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

(°C x 1.8) + 32 = °F
kV/mm x 25.4 = V/mil
mm / 25.4 = inches
N x 0.225 = lb
N/mm x 5.71 = lb/in
N/mm² x 145 = psi
MPa x 145 = psi
N·m x 8.851 = lb·in
N·m x 0.738 = lb·ft
N·mm x 0.142 = oz·in
mPa·s = cP

Note

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, **Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits.** The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patents that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

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